

WLCSP15_6-3-6

wafer level chip-size package; 15 bumps (6-3-6)

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP
Package type industry code	WLCSP15
Package style descriptive code	UC (uncased chip)
Package style suffix code	NA (not applicable)
Package body material type	X (other)
Mounting method type	S (surface mount)
Issue date	11-2-2010

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
n ₂	actual quantity of termination	-	-	15	-	



2. Package outline

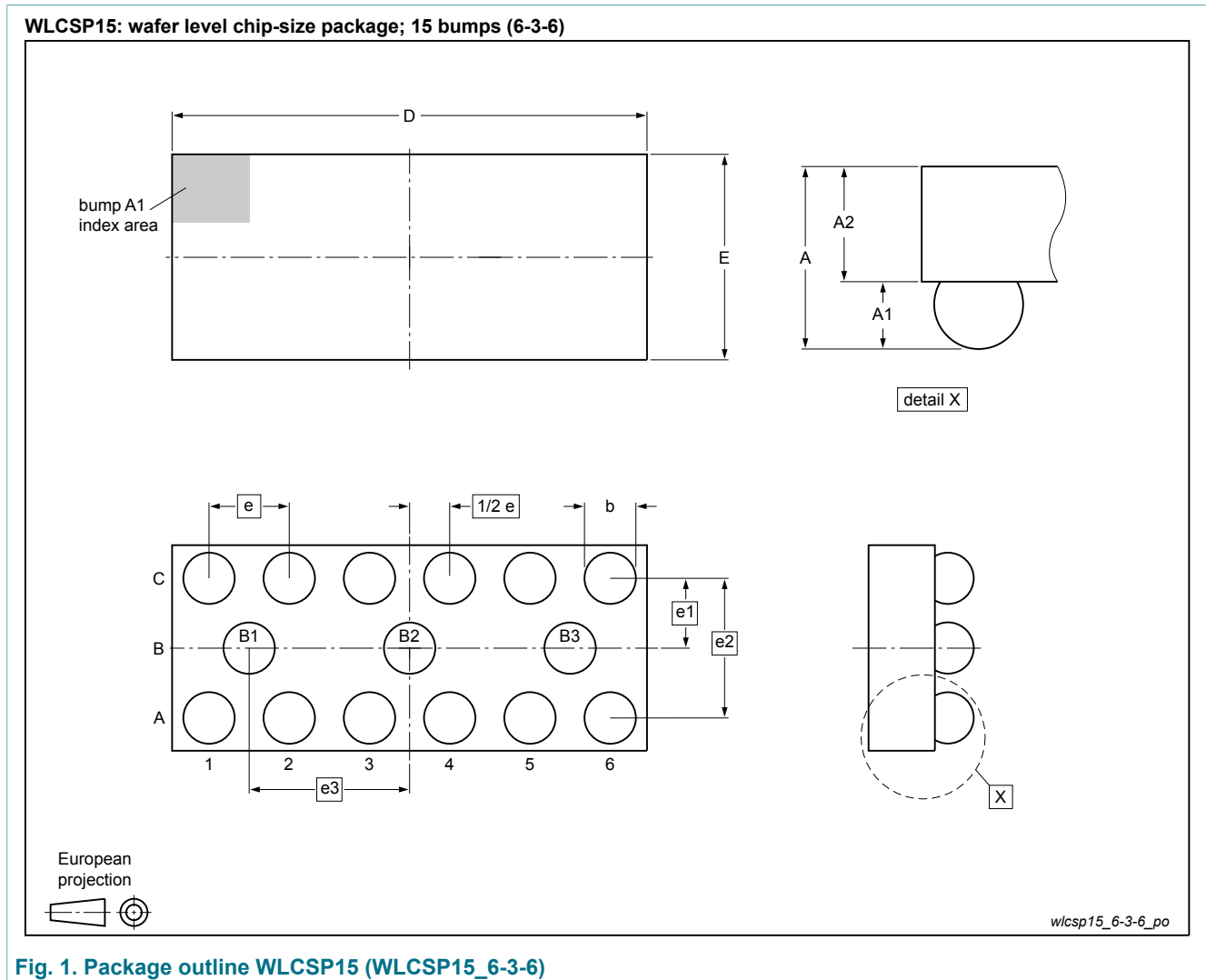


Fig. 1. Package outline WLCSP15 (WLCSP15_6-3-6)

3. Legal information

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